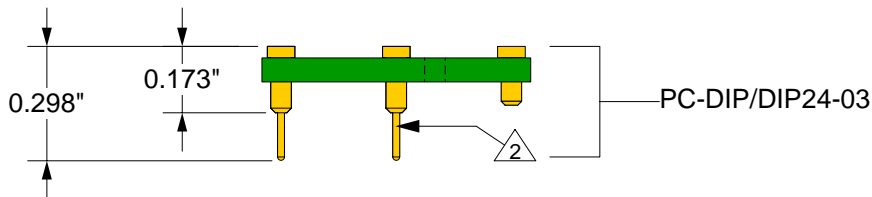
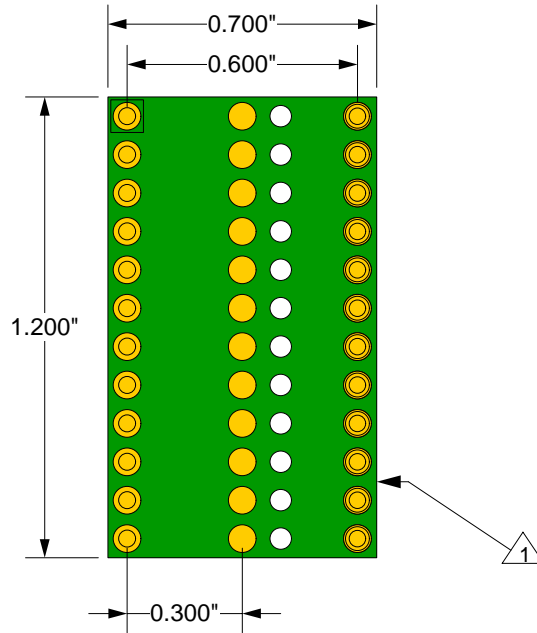
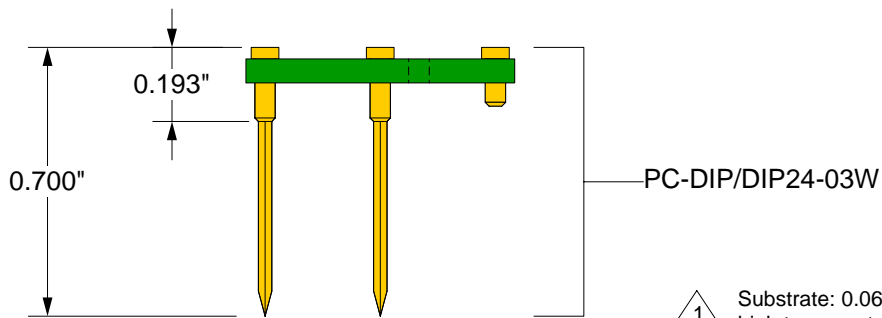


Top View




Side View



- △1 Substrate: 0.0625"±0.007" FR4/G10 or equivalent high temp material. 1/2 oz. Cu clad. SnPb plating
- △2 Pins: shell material- Brass Alloy 360 1/2 hard; finish- 10µ" Au over 50µ" Nil (min.). Contact material- BeCu; finish 10µ" Au over 100µ" Ni (min.)

All tolerances: ±0.005" (unless stated otherwise). Materials and specifications are subject to change without notice.

<b>PC-DIP/DIP24-03(W) Drawing</b>		Status: Released	Scale: 2:1	Rev B
 <p>© 1998 IRONWOOD ELECTRONICS, INC.          Tele: (800) 404-0204          www.ironwoodelectronics.com</p>	Drawing: P Jasmin		Date: 09/07/89	
	File: PC-DIP/DIP24-03 Dwg, MC		Modified: 11/15/07	